

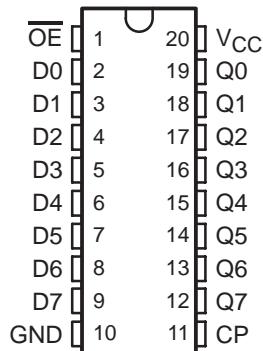
CD74HCT574-Q1
**HIGH-SPEED CMOS LOGIC OCTAL D-TYPE FLIP-FLOP
 3-STATE, POSITIVE-EDGE TRIGGERED**
 SCLS570A – FEBRUARY 2004 – REVISED APRIL 2008

- Qualified for Automotive Applications
- Buffered Inputs
- Common 3-State Output-Enable Control
- 3-State Outputs
- Bus-Line Driving Capability
- Typical Propagation Delay (Clock to Q):
 15 ns at $V_{CC} = 5\text{ V}$, $C_L = 15\text{ pF}$, $T_A = 25^\circ\text{C}$
- Fanout (Over Temperature Range)
 - Standard Outputs ... 10 LSTTL Loads
 - Bus Driver Outputs ... 15 LSTTL Loads
- Balanced Propagation Delay and Transition Times

description/ordering information

The CD74HCT574 is an octal D-type flip-flop with 3-state outputs and the capability to drive 15 LSTTL loads. The eight edge-triggered flip-flops enter data into their registers on the low-to-high transition of the clock (CP). The output enable (\overline{OE}) controls the 3-state outputs and is independent of the register operation. When \overline{OE} is high, the outputs are in the high-impedance state.

M OR PW PACKAGE
 (TOP VIEW)



ORDERING INFORMATION†

TA	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – M	Tape and reel	CD74HCT574QM96Q1	HCT574Q
	TSSOP – PW	Tape and reel	CD74HCT574QPWRQ1	HCT574Q

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.



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FUNCTION TABLE

INPUTS			OUTPUT
\overline{OE}	CP	D	Q
L	↑	H	H
L	↑	L	L
L	L	X	Q_0
H	X	X	Z

NOTE: H = High voltage level (steady state)

L = Low voltage level (steady state)

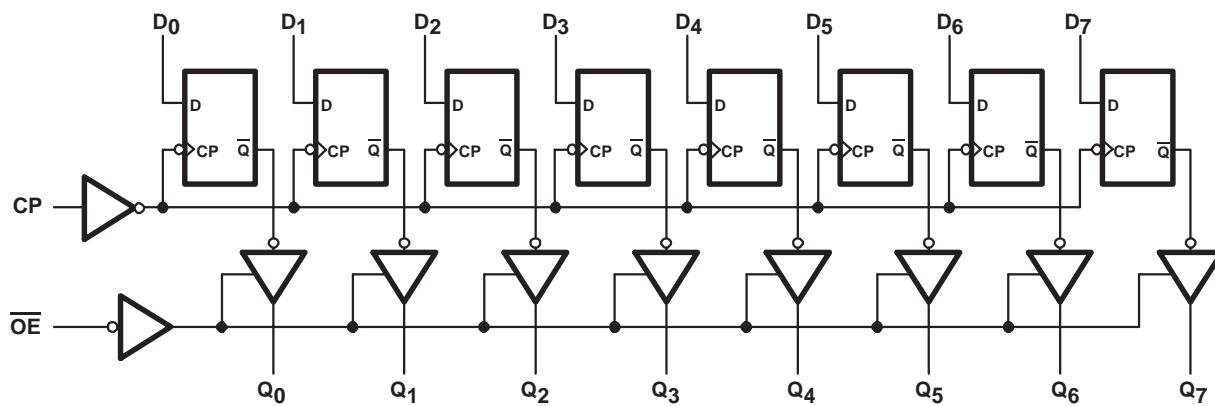
X = Don't care

↑ = Transition from low to high level

Q_0 = Level before the indicated steady-state conditions were established

Z = High-impedance state

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages referenced to GND unless otherwise specified.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V _{CC}	Supply voltage	4.5 5.5		V
V _{IH}	High-level input voltage	V _{CC} = 4.5 V to 5.5 V		V
V _{IL}	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V		0.8 V
V _I	Input voltage	0 V _{CC}		V
V _O	Output voltage	0 V _{CC}		V
t _{tr}	Input transition (rise and fall) time	V _{CC} = 2 V		0 1000
		V _{CC} = 4.5 V		0 500
		V _{CC} = 6 V		0 400
T _A	Operating free-air temperature	-40 125		°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	I _O (mA)	V _{CC}	T _A = 25°C			T _A = -40°C TO 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	CMOS loads	-0.02	4.5 V	4.4		4.4		V
		TTL loads	-6	4.5 V	3.98		3.7		
V _{OL}	V _I = V _{IH} or V _{IL}	CMOS loads	0.02	4.5 V		0.1		0.1	V
		TTL loads	6	4.5 V		0.26		0.4	
I _I	V _I = V _{CC} or GND		0	5.5 V		±0.1		±1	µA
I _{OZ}	V _I = V _{IL} or V _{IH} , V _O = V _{CC} or GND			6 V		±0.5		±10	µA
I _{CC}	V _I = V _{CC} or GND	0	5.5 V			8		160	µA
ΔI _{CC}	V _I = V _{CC} – 2.1 V, See Note 4		4.5 V to 5.5 V		100	360		490	µA
C _{IN}	C _L = 50 pF					10		10	pF
C _{OUT}	3-state					20		20	pF

NOTE 4: For dual-supply systems, theoretical worst-case (V_I = 2.4 V, V_{CC} = 5.5 V) specification is 1.8 mA.

HCT input loading

TYPE	INPUT	UNIT LOADS [†]	
		MIN	MAX
'574	D0–D7	0.4	
	CP	0.75	
	OE	0.6	

[†]Unit load is ΔI_{CC} limit specified in electrical characteristics table, e.g., 360 µA max at 25°C.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	V _{CC}	T _A = 25°C		T _A = -40°C TO 125°C		UNIT
		MIN	MAX	MIN	MAX	
f _{max} Maximum clock frequency	4.5 V	30		20		MHz
t _w Clock pulse duration	4.5 V	16		24		ns
t _{su} Setup time, data before clock↑	4.5 V	12		18		ns
t _h Hold time, data after clock↑	4.5 V	5		5		ns

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	V _{CC}	T _A = 25°C			T _A = -40°C TO 125°C		UNIT
					MIN	TYP	MAX	MIN	MAX	
t _{pd}	CP	Q	C _L = 50 pF	4.5 V		33		50		ns
			C _L = 15 pF	5 V		15				
t _{dis}	OE	Q	C _L = 50 pF	4.5 V		28		42		ns
			C _L = 15 pF	5 V		11				
t _{en}	OE	Q	C _L = 50 pF	4.5 V		30		45		ns
			C _L = 15 pF	5 V		12				
t _t		Q	C _L = 50 pF	4.5 V			12		18	ns
f _{max}	CP		C _L = 15 pF	5 V		60				MHz

operating characteristics, V_{CC} = 5 V, T_A = 25°C, input t_r, t_f = 6 ns

PARAMETER			TYP	UNIT
C _{pd}	Power dissipation capacitance (see Note 5)		47	pF

NOTE 5: C_{pd} is used to determine the dynamic power consumption (P_D), per package.

$$P_D = (C_{PD} \times V_{CC}^2 \times f_I) + \sum (C_L \times V_{CC}^2 \times f_O)$$

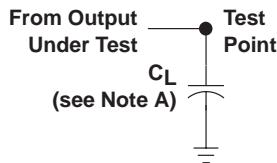
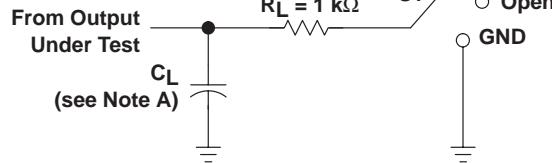
f_I = input frequency

f_O = output frequency

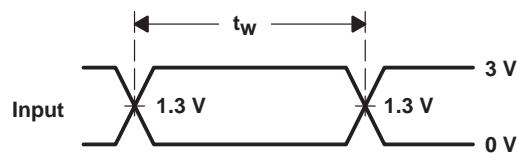
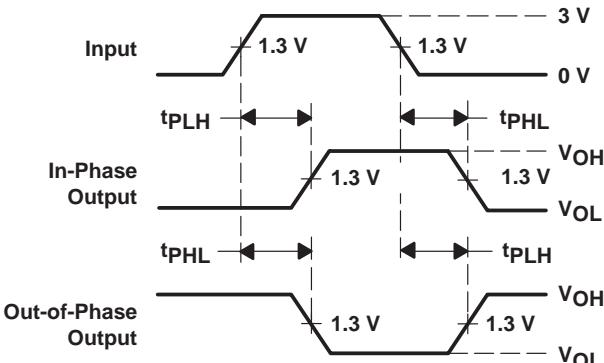
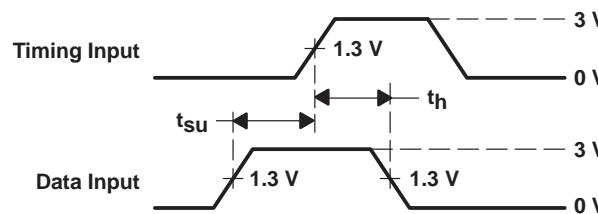
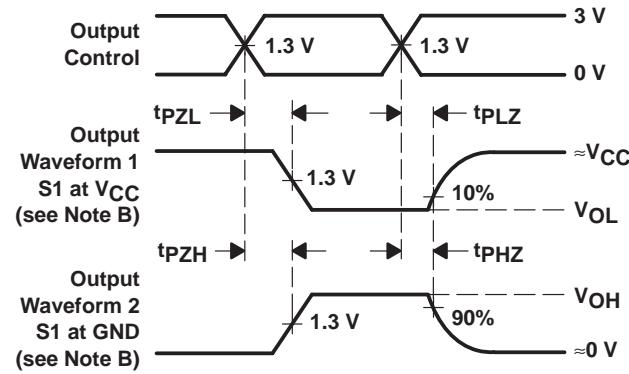
C_L = output load capacitance

V_{CC} = supply voltage

PARAMETER MEASUREMENT INFORMATION

LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTSLOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS

TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	V _{CC}
tPHZ/tPZH	GND
Open Drain	V _{CC}

VOLTAGE WAVEFORMS
PULSE DURATIONVOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTSVOLTAGE WAVEFORMS
SETUP AND HOLD TIMESVOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES:

- C_L includes probe and jig capacitance.
- Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O = 50 \Omega$, $t_r \leq 6$ ns, $t_f \leq 6$ ns.
- The outputs are measured one at a time, with one input transition per measurement.
- All parameters and waveforms are not applicable to all devices.
- t_{PLH} and t_{PHL} are the same as t_{pd} .
- t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- t_{PZH} and t_{PZL} are the same as t_{en} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD74HCT574QM96G4Q1	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT574QM96Q1	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT574QPWRG4Q1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD74HCT574QPWRQ1	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF CD74HCT574-Q1 :

- Catalog: [CD74HCT574](#)
- Enhanced Product: [CD74HCT574-EP](#)
- Military: [CD54HCT574](#)

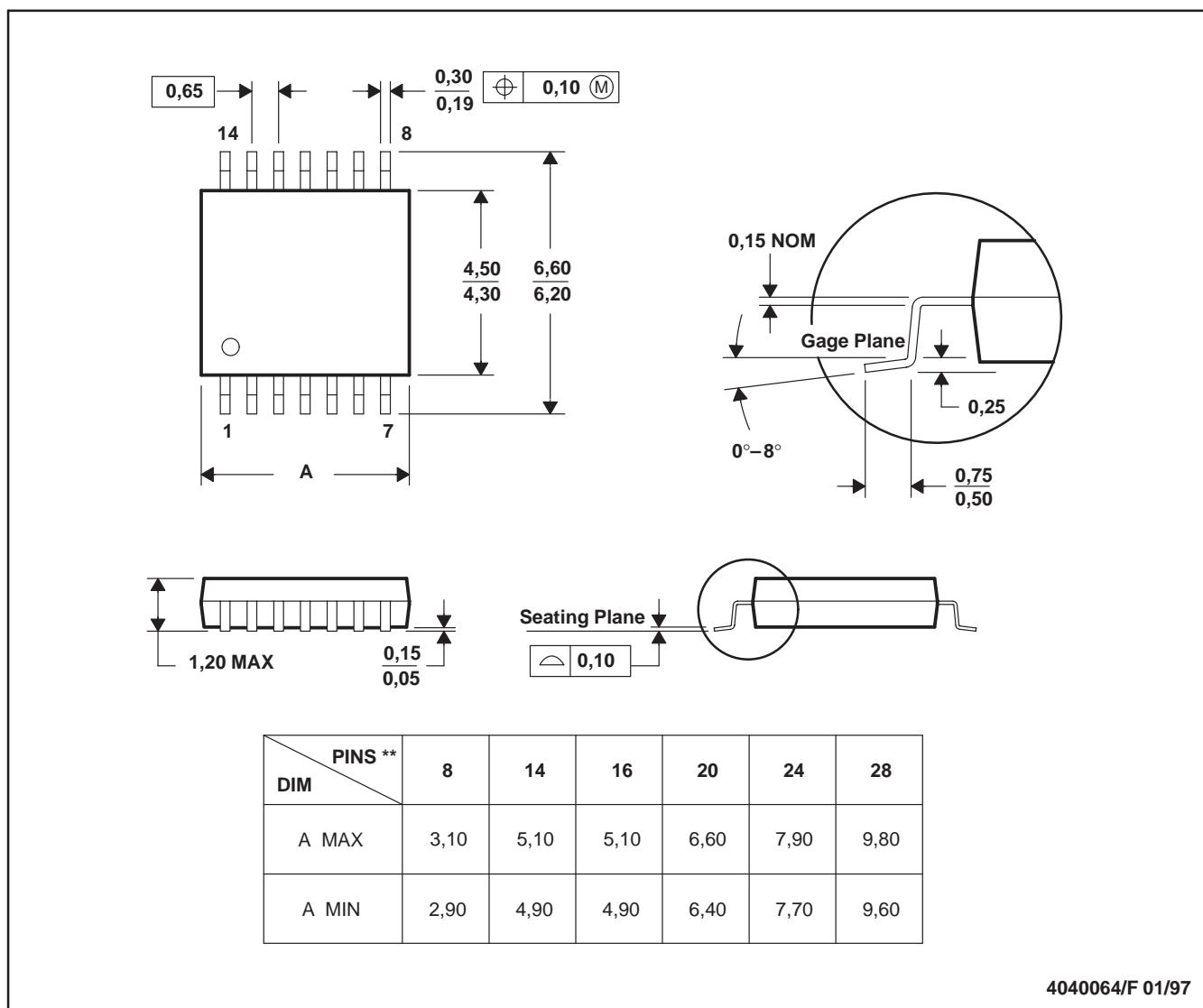
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN

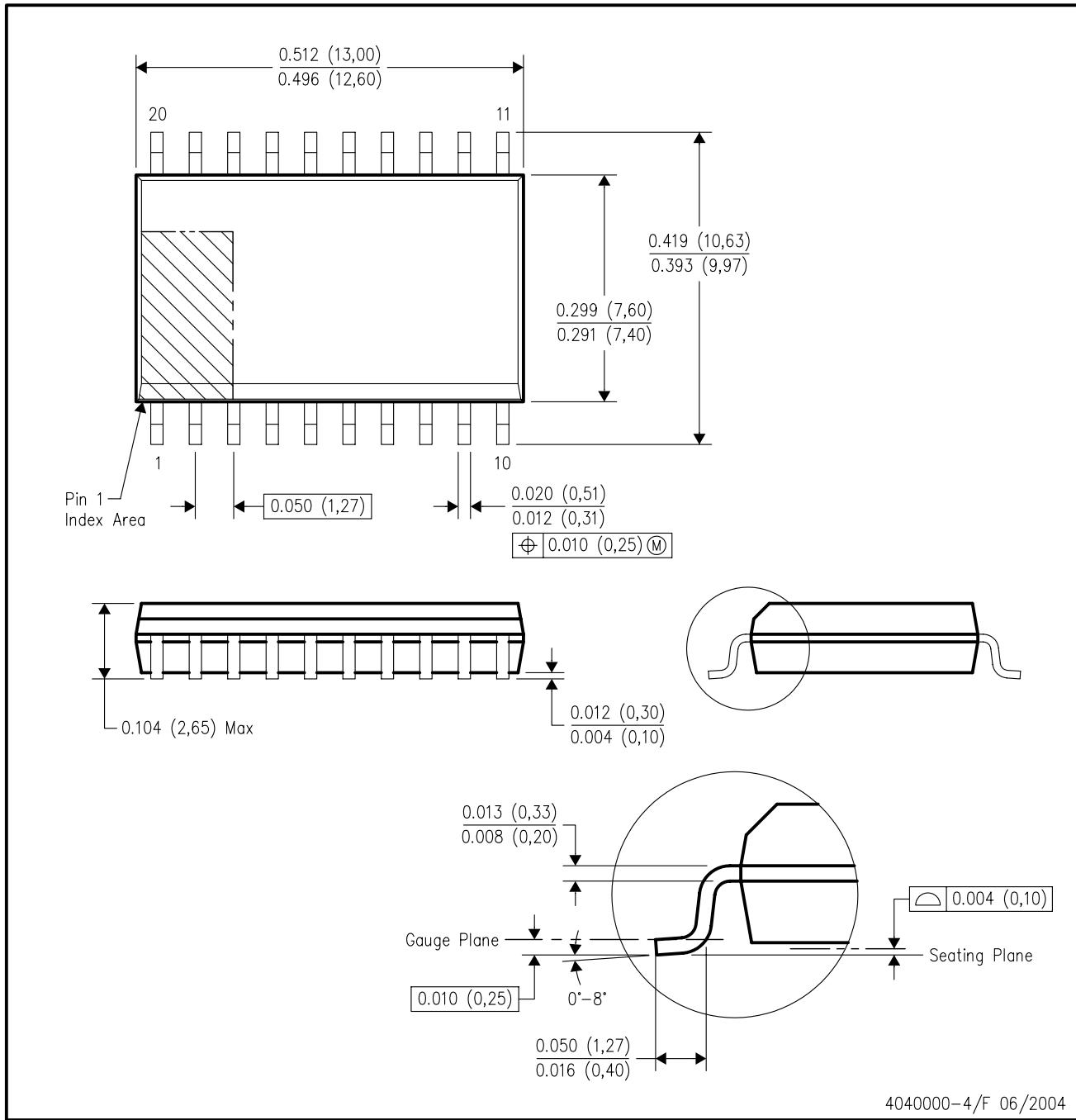


NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- Falls within JEDEC MO-153

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MS-013 variation AC.

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